

Notification Number:	20220711001.0	Notification Date:	July 22, 2022
Title:	Datasheet for DRV8243-Q1, DRV8244-Q1, and DRV8245-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



Changes from Revision A (January 2022) to Revision B (July 2022)	Page
• Device comparison - Removed pre-production information, slew rate and off-state diagnostics feature exceptions for DRV8245HRXZQ1 and DRV8244SRYJQ1.....	3
• Corrected pin name typo for PH/IN2.....	10
• EC table - R _{LVL3of3} for MODE pin increased to 250 KΩ minimum.....	13
• EC table - Updated typical R _{ON} values.....	13
• Typical characteristics - Corrected FET RON plot, improved A _{IPROP1} plot.....	26
• Block diagram for P-variant - Corrected VDD pin typo.....	29
• Feature description for PWM mode - Removed pre-production information.....	33
• Feature description for Register - Pin control - Removed pre-production information.....	35
• Feature description for SR - Removed pre-production information and duplication of SR tables (Refer EC table instead).....	36
• Feature description for ITRIP regulation - Removed pre-production information, added note on linear ITRIP levels using external DAC.....	36
• Feature description for DIAG pin (HW variant only) - Corrected behavior for LVL5 setting.....	38
• Feature description update for OLA - Added clarification on fault clearing when drive direction is reversed...	43
• Functional states - Removed pre-production information.....	45
• SDO frame - Removed pre-production information.....	48
• User registers - Removed pre-production information.....	53
• Typical application - Added recommendations for EMC.....	60

Changes from Revision A (January 2022) to Revision B (July 2022)	Page
• Device comparison - Removed pre-production information, slew rate and off-state diagnostics feature exceptions for DRV8245HRXZQ1 and DRV8244SRYJQ1.....	4
• Corrected pin name typo for PH/IN2.....	12
• EC table - V_{VM_REV} typical value changed to 1.4 V.....	13
• EC table - $R_{LVL3of3}$ for MODE pin increased to 250 K Ω minimum.....	15
• EC table - Updated typical R_{ON} values, updated R_{HI-Z} values to a range of (1.5 to 9.5 K Ω).....	15
• EC table - Removed the limitations for certain slew rate settings (SR = 3'b000, 3'b001, 3'b010), corrected SR_{HS_ON} to 6.5 V/ μ sec	17
• EC table - Reduced IPROPI_LIM min value to 4.5 V.....	18
• EC table - Increased I_{PD_OLA} range to 1 - 9 mA.....	19
• Typical characteristics - Corrected FET RON plot, improved A_{IPROPI} plot.....	28
• Block diagram for P-variant - Corrected VDD pin typo.....	31
• Feature description for PWM mode - Removed pre-production information.....	35
• Feature description for Register - Pin control - Removed pre-production information.....	37
• Feature description for SR - Removed limitations for settings 0x0, 0x1 and 0x2 for DRV8244SRYJQ1, removed pre-production information and duplication of SR tables (Refer Electrical Characteristics table instead). Also corrected SR_{HS_ON} to 6.5 V/ μ sec.....	38
• Feature description for ITRIP regulation - Removed pre-production information, added note on linear ITRIP levels using external DAC.....	38
• Feature description for DIAG pin (HW variant only) - Corrected behavior for LVL5 setting.....	40
• Feature description update for OLP - Removed feature exception for DRV8244SRYJQ1.....	43
• Feature description update for OLA - Added clarification on fault clearing when drive direction is reversed...	45
• Functional states - Removed pre-production information.....	47
• SDO frame - Removed pre-production information.....	50
• User registers - Removed pre-production information.....	55
• Typical application - Added recommendations for EMC, improved pin use-case description, corrected pin number in the application diagram for the HW variant in VQFN-HR package.....	62

Changes from Revision A (January 2022) to Revision B (July 2022)	Page
• Device comparison - Removed pre-production information, slew rate and off-state diagnostics feature exceptions for DRV8245HRXZQ1 and DRV8244SRJQ1.....	4
• Corrected pin name typo for PH/IN2.....	12
• EC table - V_{VM_REV} typical value changed to 1.4 V.....	13
• EC table - $R_{LVL3of3}$ for MODE pin increased to 250 K Ω minimum.....	15
• EC table - Updated typical R_{ON} values, updated R_{HI-Z} values to a range of (0.9 to 5.63 K Ω).....	15
• EC table - Removed the limitations for LVL2 slew rate setting.....	17
• EC table - Reduced IPROPI_LIM min value to 4.5 V.....	18
• EC table - Increased I_{PD_OLA} range to 2 - 13.82 mA.....	19
• Typical characteristics - Corrected FET RON plot and LS OCP plot, improved A_{IPROPI} plot.....	28
• Block diagram for P-variant - Corrected VDD pin typo.....	31
• Feature description for PWM mode - Removed pre-production information.....	35
• Feature description for Register - Pin control - Removed pre-production information.....	37
• Feature description for SR - Removed limitations for LVL2 for DRV8245HRXZQ1, removed pre-production information and duplication of SR tables (Refer Electrical Characteristics table instead).....	38
• Feature description for ITRIP regulation - Removed pre-production information, added note on linear ITRIP levels using external DAC.....	38
• Feature description for DIAG pin (HW variant only) - Corrected behavior for LVL5 setting.....	41
• Feature description update for OLP - Removed feature exception for DRV8245HRXZQ1.....	43
• Feature description update for OLA - Added clarification on fault clearing when drive direction is reversed...	45
• Functional states - Removed pre-production information.....	47
• SDO frame - Removed pre-production information.....	50
• User registers - Removed pre-production information.....	55
• Typical application - Added recommendations for EMC, improved pin use-case description, corrected pin number in the application diagram for the HW variant in VQFN-HR package.....	62

The datasheet number will be changing.

Device Family	Change From:	Change To:
DRV8243-Q1	SLVSG23A	SLVSG23B
DRV8244-Q1	SLVSG24A	SLVSG24B
DRV8245-Q1	SLVSFJ1A	SLVSFJ1B

These changes may be reviewed at the datasheet links provided.

<https://www.ti.com/product/DRV8243-Q1>

<https://www.ti.com/product/DRV8244-Q1>

<https://www.ti.com/product/DRV8245-Q1>

Error! Bookmark not defined.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:			
DRV8245HQRXZRQ1	DRV8243HQRXYRQ1	DRV8244SQRYJRQ1	

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.